12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260811001.1	PCN Issued	August 12, 2026
Qualification of RFAB as an additional Fab site, Die Revision & BOM options for select devices		Sample request deadline:	October 11, 2026
		Estimated 1st ship date:	November 10, 2026
***Sample requests received after** October 11, 2026* **will not be supported.**			

Change type(s)
Assembly Material Packing/Shipping/Labeling Wafer Fab Site

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site, Die Revision & BOM options for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DMOS6	LBC9	300mm	RFAB	LBC9	300mm

The die was also changed as a result of the process change.

Construction Differences are as follows:

	Current	Additional
Lead finish	NiPdAu	Matte Sn

Qual details are provided in the Qual Data Section.

Reason for Change:	Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Physical aspects of the device have changed. Request the Supporting Data Packet (SDP) for more details on the changes.

Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DMOS6	DM6	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
A0, A1	**B0**

Sample product shipping label (not actual product label):

Products Affected:

DRV8210DSGR	DRV8212DSGR	DRV8212PDSGR.A
DRV8210PDSGR	DRV8212PDSGR	

Qualification Report
DRV8212xDSGR
Approve Date 11-June-2026

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV8212DSGR	Qual Device: DRV8212PDSGR	QBS Package, Product Reference: DRV8212PDSGR	QBS Package, Product Reference: DRV8210PDSGR	QBS Package Reference: LM5155DSST	QBS Package Reference: UCC27614DSGR	QBS Process Reference: LM70880QRRXRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	3/231/0	1/77/0	NA
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	3/231/0	-	NA
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	1/77/0	1/77/0	3/231/0	1/77/0	NA
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	1/77/0	3/231/0	1/77/0	NA
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	NA	NA	NA	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	NA	NA	NA	3/2400/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/22/0	-	-	-	-	-	NA
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/3/0	1/3/0	1/6/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	3/90/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device DRV8212DSGR is qualified at MSL1 260C
Qual Device DRV8212PDSGR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
The qualification conditions stated in the table above apply to the qual device. The QBS references have either the same conditions or JEDEC-standard equivalent conditions.
Any tests not applicable to a certain type of QBS reference were marked as “NA”. Example, for a QBS Package Reference, package tests were stated, and process tests were marked as “NA”.
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2509-032

Qualification Report
DRV8210xDSGR
Approve Date 03-JUNE -2026

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV8210DSGR	Qual Device: DRV8210PDSGR	QBS Package, Product Reference: DRV8210PDSGR	QBS Package Reference: LM5155DSST	QBS Package Reference: UCC27614DSGR	QBS Package Reference: TPS51604DSGR-S	QBS Process Reference: LM70880QRRXRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	1/77/0	3/231/0	1/77/0	-	NA
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	1/77/0	3/231/0	1/77/0	3/231/0	NA
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	1/77/0	3/231/0	1/77/0	3/231/0	NA
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	1/77/0	3/231/0	1/77/0	3/231/0	NA
HTOL	B1	Life Test	125C	1000 Hours	-	-	NA	NA	NA	NA	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	NA	NA	NA	NA	3/2400/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-	-	1/5/0	NA
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	NA	NA	NA	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	1/3/0	NA	NA	NA	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/3/0	NA	NA	NA	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	NA	NA	NA	3/90/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device DRV8210DSGR is qualified at MSL1 260C
Qual Device DRV8210PDSGR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
The qualification conditions stated in the table above apply to the qual device. The QBS references have either the same conditions or JEDEC-standard equivalent conditions.
Any tests not applicable to a certain type of QBS reference were marked as “NA”. Example, for a QBS Package Reference, package tests were stated, and process tests were marked as “NA”.
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2509-031

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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